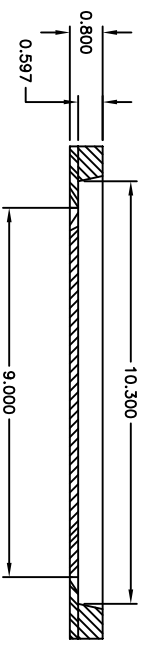
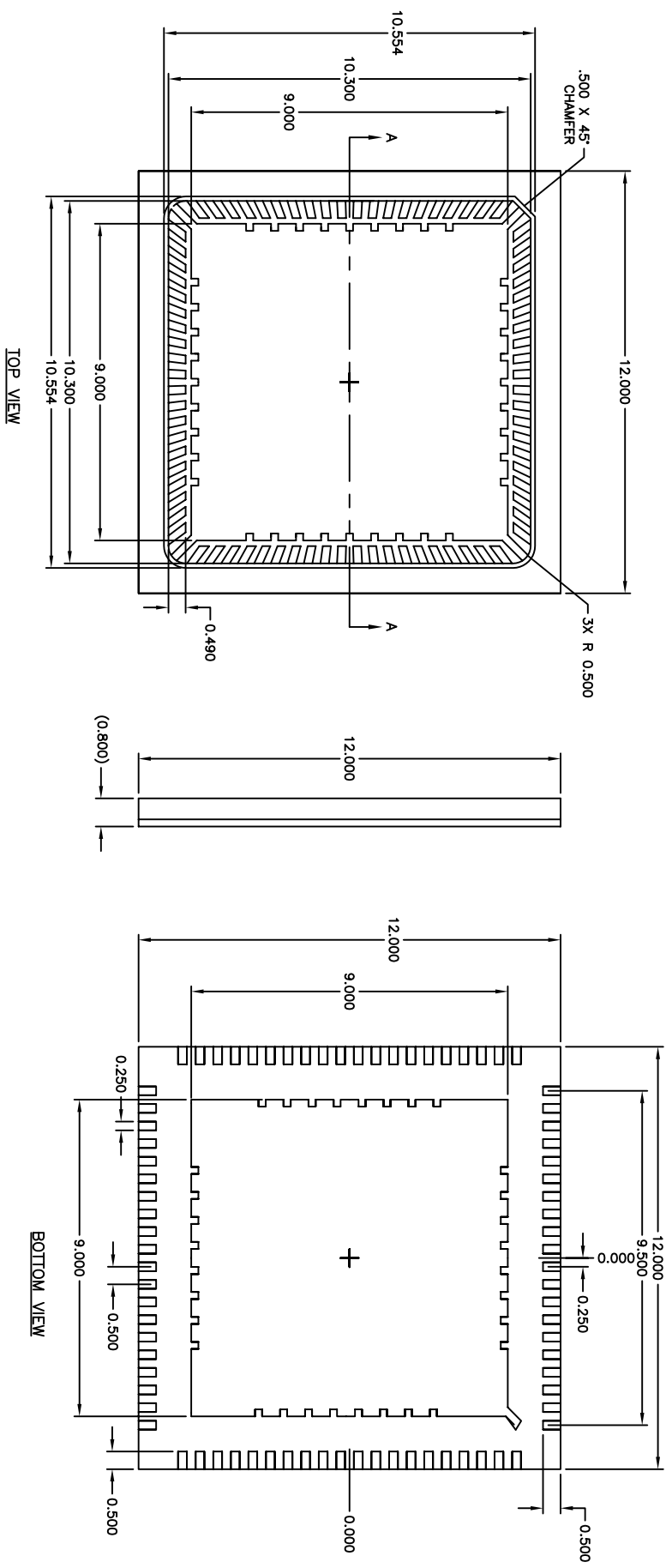


SEMPAC REVISIONS			APPROVED
ECON NO.	DATE	DESCRIPTION	
10819	12/04/06	PRODUCTION RELEASE	D.MORRIS



- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
  3. LEAD FRAME: COPPER, 194 FH.
  4. LEAD FINISH: FULL GOLD PLATE.
  5. FRAME THICKNESS: 0.2030 ±.0076
  6. DIE PAD: 9.000mm x 9.000mm.



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: X.XXX ± 0.015 X.XXXX ± .1° DO NOT SCALE DRAWING

DRAWN BY	C. CRUZ	DATE	12/04/06
APP BY	P. FLASKERUD	DATE	12/04/06

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80 LEAD 12mm X 12mm  
 MLP Open-Pak™

SIZE	A	PART NO.	MLP12X12-80-OP-01	REV	2
SCALE	NONE	FILE	MLP12X12-80-OP-01-R2.DWG	SHEET	1 OF 1